

ABSTRACT OF THE DISCLOSURE

A lower interconnection connected to a short circuit or a spare circuit is formed on a substrate, and a dielectric film is formed so as to cover the lower interconnection. An opening section is formed in the dielectric film so as to extend to an upper surface of the lower interconnection. A plug is formed in the opening section. An upper interconnection is formed on the plug by way of a predetermined void and is connected to a load circuit. When the upper interconnection and the lower interconnection are subjected to antifuse connection, electromigration is induced in an aluminum interconnection on the upper interconnection, thereby interconnecting the upper interconnection and the plug.